

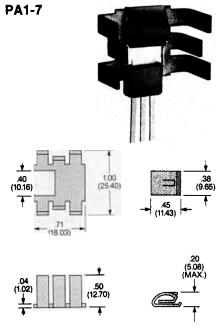
Free-standing heat dissipator and clip assembly

- Beryllium copper clip is designed to provide high clamping pressure, which assures low thermal resistance between dissipator and semiconductor, allowing a 150% power increase in natural convection to more than 400% in forced air.

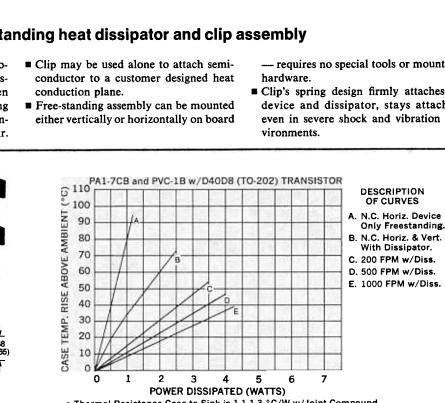
- requires no special tools or mounting
- Clip's spring design firmly attaches to device and dissipator, stays attached even in severe shock and vibration en-

DESCRIPTION OF CURVES

Only Freestanding.

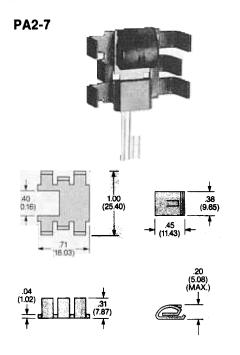


Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings

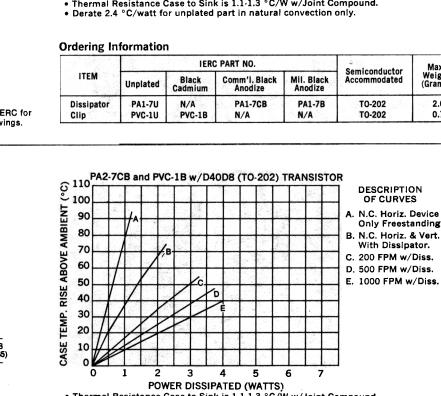


- Thermal Resistance Case to Sink is 1.1-1.3 °C/W w/Joint Compound.
- Derate 2.4 °C/watt for unplated part in natural convection only.

ITEM		IER	Samla and water	Max.		
	Unplated	Black Cadmium	Comm'l. Black Anodize	Mil. Black Anodize	Semiconductor Accommodated	Weight (Grams)
Dissipator Clip	PA1-7U PVC-1U	N/A PVC-1B	PA1-7CB N/A	PA1-7B N/A	T0-202 T0-202	2.0 0.7



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



- Thermal Resistance Case to Sink is 1.1-1.3 °C/W w/Joint Compound.
 Derate 2.4 °C/watt for unplated part in natural convection only.

Ordering Information

ITEM		IERO	Comisson ductor	Max.		
	Unplated	Black Cadmium	Comm'l. Black Anodize	Mil. Black Anodize	Semiconductor Accommodated	Weight (Grams)
Dissipator Clip	PA2-7U PVC-1U	N/A PVC-1B	PA2-7CB N/A	PA2-7B N/A	T0-202 T0-202	1.5 0.7